

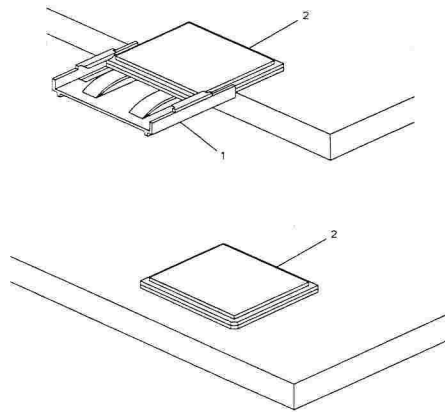
CAUTION



ELECTROSTATIC SENSITIVE

The die is an electrostatic sensitive device. Special handling methods and equipment must be used to prevent damage.

1. Ensure inspection area is ESD compliant. A clean room environment is desirable to minimize foreign material contamination.
2. Carefully remove chip sentry carriers from shipping containers.
3. Align non-restricted side of chip sentry carrier along table edge so that clip (1) is just under table edge and waffle pack (2) edge can be moved freely onto table surface.
4. Holding bottom of clip (1) with index fingers, press top of waffle pack (2) with thumbs and slide waffle pack onto table surface.



5. Place a couple of empty waffle packs onto the microscope stage.
6. Carefully pick up the unclipped waffle pack & gently place it on top of the empty waffle packs which are on the microscope stage.

Do not drop or jar the unclipped waffle pack because the enclosed small die will flip or fall out of their waffle pack cells.

7. Prior to removing lid, tap lightly on the lid to ensure die are settled to the bottom of the waffle pack.

Using two hands, grasp two edges of the waffle pack bottom with one hand & two edges of the waffle pack top with the other hand, and slowly lift top as though hinged. If difficulty is experienced separating the lid from the bottom, see step 6 on the reverse side of these instructions.

Again, do not drop or jar the waffle pack or die will flip and/or fall out of their cells.

8. Utilize fine tip tweezers (~0.5 mils at tip) with smooth sides to remove die from the waffle pack cells. Off-the-shelf tweezers are generally 2 mils at the tip. These will have to be honed/filed down using a ceramic or equivalent grinding surface. This filing operation should take about 30 to 45 minutes to complete. Care must be taken when handling these tweezers or damage may occur.

Note: Tweezers must be kept clean with frequent alcohol dips (e.g., methyl alcohol), and then dried by inserting into a soft cork (or use a lint-free wipe).

10. Always pick die along the longest dimension.